# XN01216 (XN1216)

### Silicon NPN epitaxial planer transistor

### For switching/digital circuits

#### Features

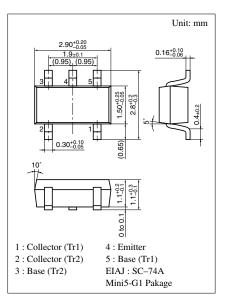
- Two elements incorporated into one package. (Emitter-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

#### Basic Part Number of Element

• UNR1216(UN1216) × 2 elements

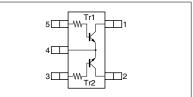
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Parameter		Symbol	Ratings	Unit
Rating of element	Collector to base voltage	V <sub>CBO</sub>	50	V
	Collector to emitter voltage	V <sub>CEO</sub>	50	V
	Collector current	I <sub>C</sub>	100	mA
Overall	Total power dissipation	P <sub>T</sub>	300	mW
	Junction temperature	Tj	150	°C
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C

#### Absolute Maximum Ratings (Ta=25°C)



### Marking Symbol: 9N

#### Internal Connection

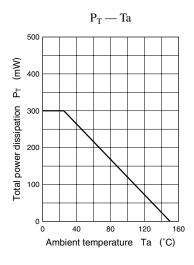


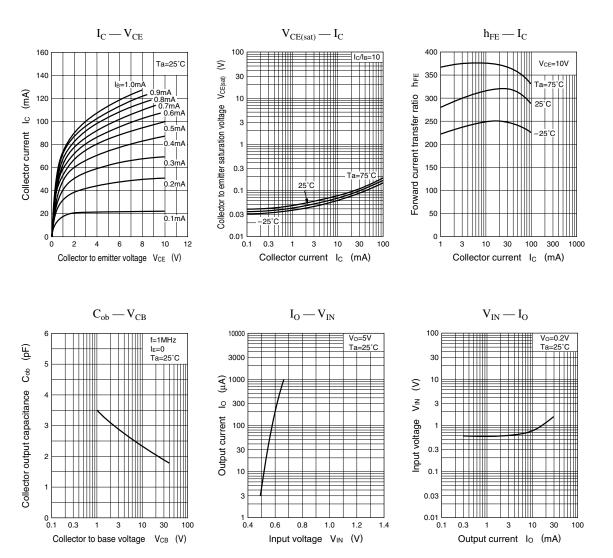
#### Parameter Symbol Conditions Unit typ max min Collector to base voltage $I_{C} = 10 \mu A, I_{E} = 0$ 50 V V<sub>CBO</sub> Collector to emitter voltage V<sub>CEO</sub> $I_{C} = 2mA, I_{B} = 0$ 50 V $V_{CB} = 50V, I_E = 0$ 0.1 I<sub>CBO</sub> μΑ Collector cutoff current $V_{CE} = 50V, I_B = 0$ I<sub>CEO</sub> 0.5 μΑ Emitter cutoff current $I_{EBO}$ $V_{EB} = 6V, I_C = 0$ 0.01 mA $V_{CE} = 10V, I_C = 5mA$ 460 Forward current transfer ratio h<sub>FE</sub> 160 $V_{CE} = 10V, I_C = 5mA$ Forward current transfer h<sub>FE</sub> ratio h<sub>FE</sub> (small/large)<sup>\*</sup> 0.5 0.99 $I_{C} = 10mA, I_{B} = 0.3mA$ 0.25 v Collector to emitter saturation voltage V<sub>CE(sat)</sub> Output voltage high level $V_{CC} = 5V, V_B = 0.5V, R_L = 1k\Omega$ 4.9 v VOH Output voltage low level VOL $V_{CC} = 5V, V_B = 2.5V, R_L = 1k\Omega$ 0.2 V $V_{CB} = 10V, I_E = -2mA, f = 200MHz$ Transition frequency $\mathbf{f}_{\mathrm{T}}$ 150 MHz Input resistance $R_1$ -30% 4.7 +30% kΩ

Electrical Characteristics (Ta=25°C)

\*1 Ratio between 2 elements

Note) The Part number in the Parenthesis shows conventional part number.





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